

TAZMO

Q1 FY2024 Financial Announcement

January – March 2024

May 14, 2024

Security Code 6266

Company Guide



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Q1 FY2024 Consolidated Financial Summary

Net sales

5,905

Million Yen

YoY Change +52.8%

Operating income

570

Million Yen

—

Ordinary income

662

Million Yen

—

Net income(*)

425

Million Yen

—

■ Overview

- Although sales and profits increased year on year, both sales and profits were lower than planned. The main factor was delays in acceptance inspections for semiconductor equipment.
- Order status is also weak. Sales of transport equipment were strong, but although there were inquiries for semiconductor equipment in particular, no orders were received in the first quarter.

Q1 FY2024 Financial Summary

(Millions of yen)	FY2023 Q1	FY2024 Q1		YoY change (%)	FY2024 estimates	cf. Plan
		Actual	Net sales ratio (%)			
Net sales	3,864	5,905	—	52.8	36,000	16.4
Gross profit	983	1,883	31.9	91.5	—	—
Operating income	△136	570	9.7	—	4,600	12.4
Ordinary income	△231	662	11.2	—	4,500	14.7
Net income attributable to owners of parent	△219	425	7.2	—	3,060	13.9

Trend in Net sales and Operating profit



(Millions of yen)	FY2023	FY2024 Q1	YoY change(%)
Current assets	39,420	41,666	5.7
Non-current assets	8,008	8,233	2.8
Property, plant and equipment	7,007	7,211	2.9
Intangible assets	157	144	△8.3
Investments and other assets	842	877	4.2
Total assets	47,428	49,899	5.2
Current Liabilities	21,380	20,527	△4.0
Non-Current Liabilities	5,952	8,802	47.9
Total liabilities	27,333	29,330	7.3
Total net assets	20,095	20,568	2.4
Equity ratio	41.7%	40.5%	△1.2P

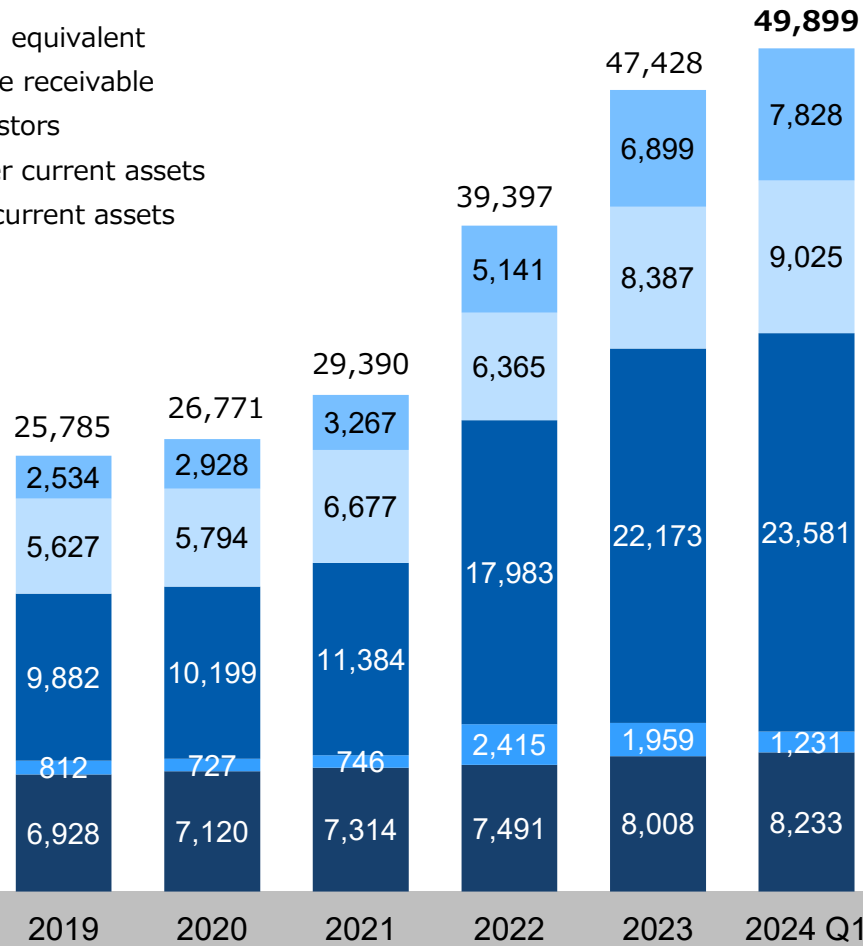
Major change

Current Assets	(Millions of yen)
Notes and accounts receivable - trade	+ 1,401
Work in process	+ 1,407
Current Liabilities	
Contract liabilities	+ 1,554
Short-term borrowings	+ 1,157
Income taxes	△712
Non-Current Liabilities	
Long-term borrowings	+2,796

Assets

(Millions of yen)

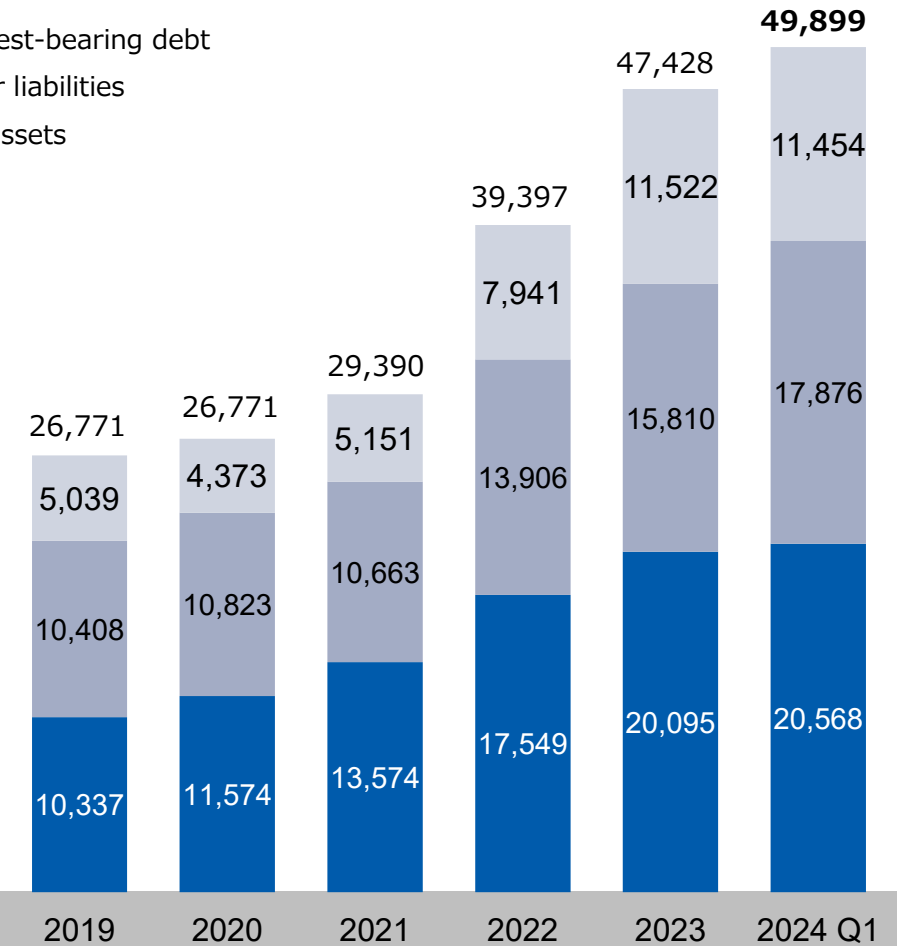
- Cash equivalent
- Trade receivable
- Investors
- Other current assets
- Noncurrent assets



Liabilities/Equity

(Millions of yen)

- Interest-bearing debt
- Other liabilities
- Net assets





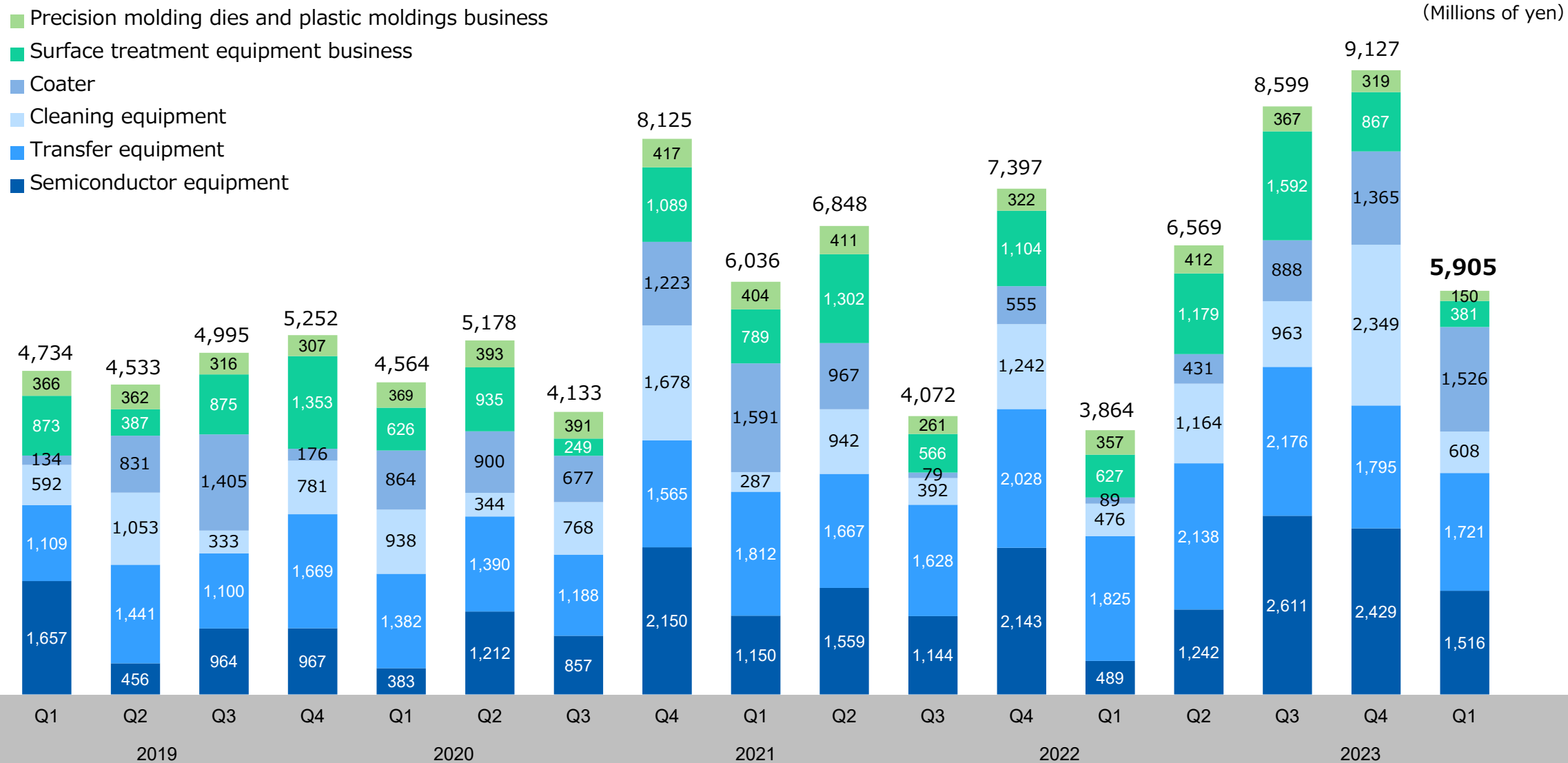
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Q1 FY2024 Segment Information

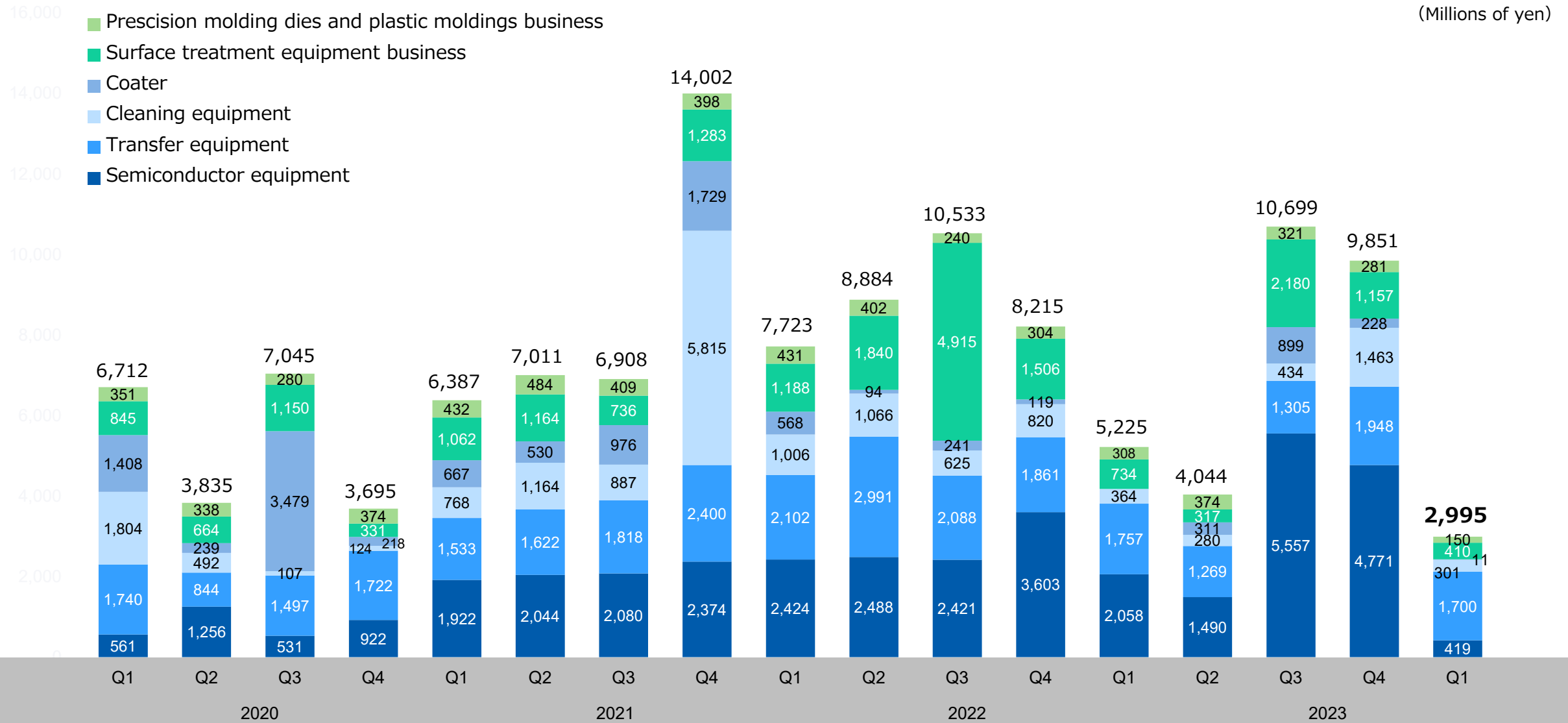
Net Sales and Operating Profit by Segment

		FY2023 Actual	FY2024 Q1 Actual	YoY change(%)	FY2024 Initial estimates	cf. Plan (%)
(Millions of yen)						
Process equipment business	Net sales	2,879	5,374	86.6	27,770	19.4
	Operating income	△62	730	—	4,250	17.2
■ Semiconductor equipment	Net sales	489	1,516	210.2	11,500	13.2
■ Transfer equipment	Net sales	1,825	1,721	△5.7	8,100	21.2
■ Cleaning equipment	Net sales	476	608	27.8	5,800	10.5
■ Coater	Net sales	89	1,526	1,611.6	2,370	64.4
Precision molding dies and plastic moldings business	Net sales	357	150	△57.9	1,700	8.8
	Operating income	8	△52	—	30	—
Surface treatment equipment business	Net sales	627	381	△39.2	6,530	5.8
	Operating income	△58	△131	—	320	—
Elimination of inter-segment transactions	Operating income	△24	△83	—	—	—
Total	Net sales	3,864	5,905	52.8	36,000	16.4
	Operating income	△136	570	—	4,600	12.4

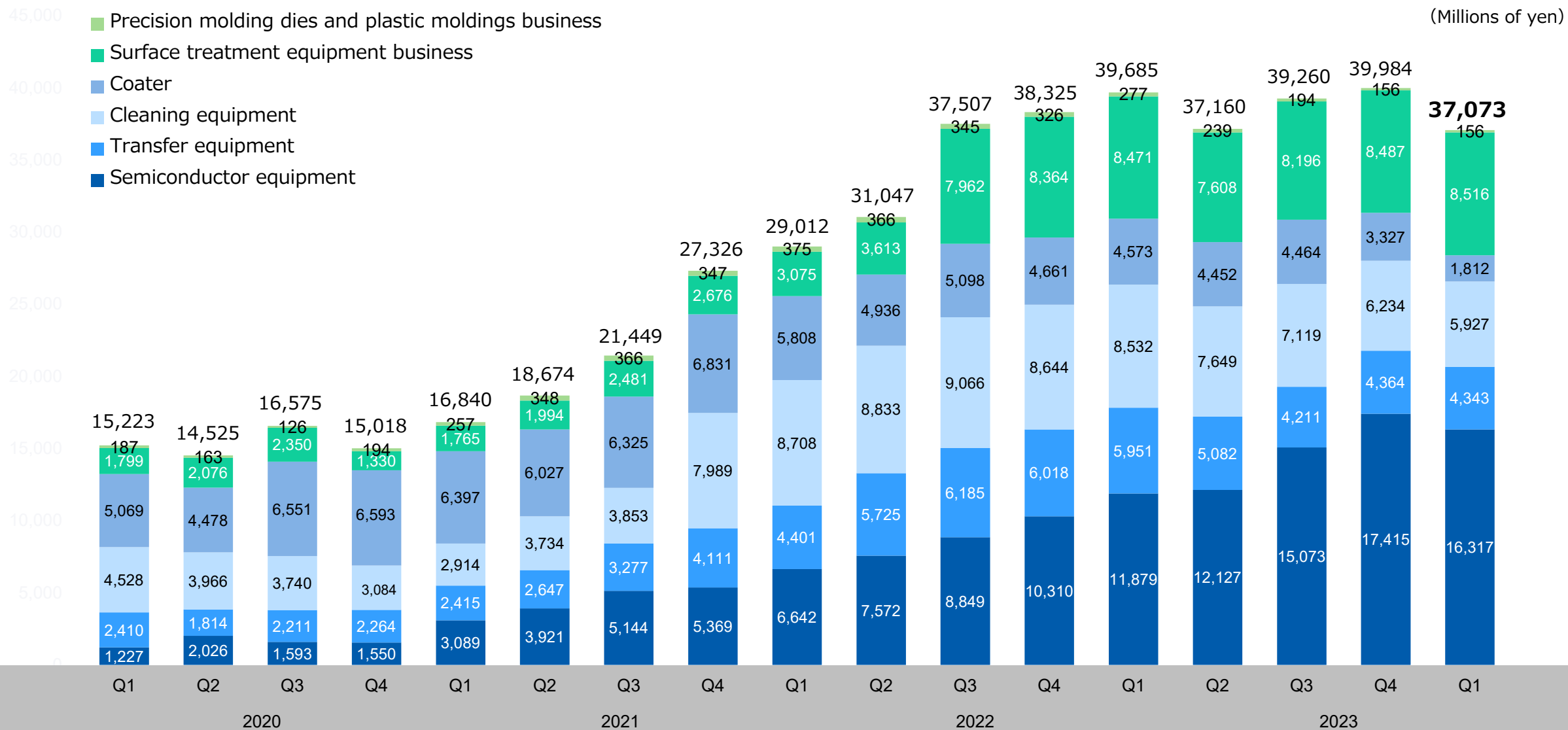
Trend in Net sales by Segment



Trend in Sales Orders by Segment



Trend in Order Backlog by Segment



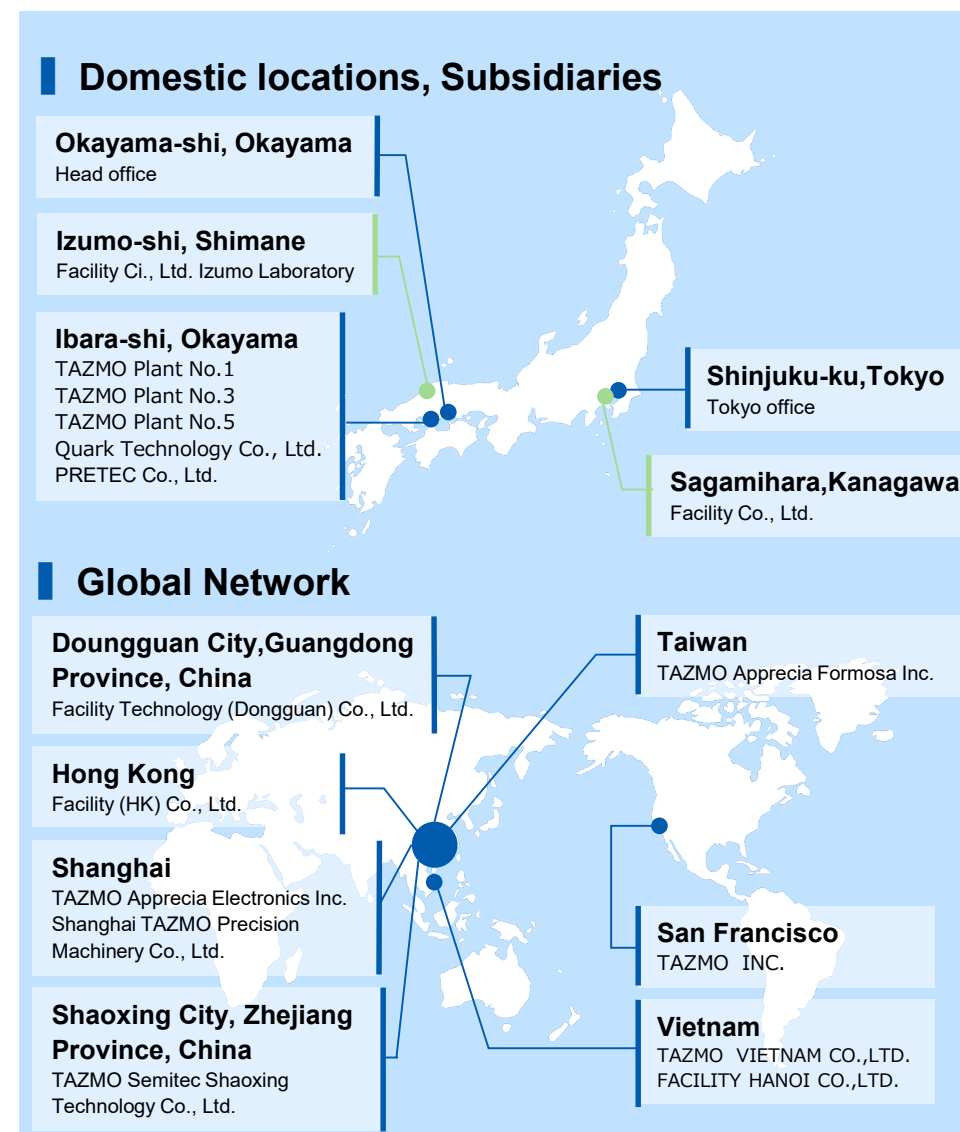


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Business Environment

- Regarding semiconductor manufacturing equipment, inquiries regarding investment in equipment for power semiconductors from next year onwards are increasing. We continue to receive inquiries regarding the advanced package. Although we did not receive any orders in the first quarter, we believe this was a timing issue. We have strong expectations for future market expansion.
- Transfer equipment is still affected by the memory/logic market conditions, but it is gradually recovering. Orders from China increase.
- Inquiries about slurry supply equipment are increasing. We are currently working to ensure that orders are received. Regarding cleaning equipment, new projects are gradually emerging. The investment period is from 2025 onwards.
- Inquiries for PLP equipment are increasing in China, Taiwan, and other countries. We are currently working to ensure that orders are received. We expect the market to expand in the future.
- The company has received inquiries both domestically and internationally for its surface treatment equipment, and has adjusted its production plans to win orders. Increased manufacturing capacity of Dongguan subsidiary. Deliveries related to board transportation, which had been delayed, are scheduled to progress this fiscal year.

Company name	TAZMO Co., Ltd.
Established	February 26, 1972
Head office	5311, Haga, Kita-ku, Okayama-shi, Okayama 701-1221, Japan
Capital	3,556,896,587 yen
Total number of issued shares	14,836,691
Number of shareholders	4,961
Number of employees	Non-consolidated 382 Consolidated 1,141
Business content	Development, Manufacturing and Sales of Semiconductor Manufacturing Equipment, Clean Transfer System, LCD Manufacturing Equipment, UV Laser Equipment, Plating Equipment, Mold・Resin Molding, Plating/Circuit formation Equipment for PCB



- 1972** ● - TAZMO Co., Ltd. is incorporated to manufacture and produce electronic components and repair industrial equipment.
- 1980** ● - Began production of molding dies, including injection molding dies.
 - Completed development of Fully-automated Photo Resist Coater; production and sales started.
- 1989** ● - Developed TFT Full-color filter manufacturing system; production and sales started.
- 1990** ● - Constructed new head office/plant at 6186 Kinoko-Cho, Ibara, Okayama
 - Developed and produced Ultra Compact Transfer System for Super Clean Room.
- 1994** ● - Began production and sales of Emboss Carrier Tape.
- 1995** ● - Began production of injection Molding Products.
- 2001** ● - Developed "CS13" series Photo Resist Coater specialized for a thicker film application; production and sales started.
- 2004** ● - Listed on the JASDAQ market.
- 2008** ● - Established TAZMO VIETNAM CO., LTD. a consolidated subsidiary, in Ho Chi Minh City, Vietnam.
- 2009** ● - Developed 10th generation compatible full-color filter manufacturing system; production and sales started.
 - Concluded a license agreement with 3M(USA) for semiconductor manufacturing equipment.
- 2013** ● - Apprecia Technology Inc. became our wholly owned subsidiary company.
 - VIETNAM CO., LTD. Constructed new factory at Long Hau Industrial Park in Long An Province, Vietnam.
- 2017** ● - Facility Co., Ltd. and Quark Technology Co., Ltd. became our wholly owned subsidiary company.
- 2018** ● - Listed on the First Section of the Tokyo Stock Exchange
- 2019** ● - Constructed a new head office at 5311 Haga Kita-ku, Okayama-shi, Okayama
- 2020** ● - Merged with Apprecia Technology Inc.
- 2022** ● - TAZMO's listing transferred to Prime Market in Tokyo Stock Exchange.
 - Increased capital to 3,495,400,000 yen through public offering.
 - Established TAZMO SEMITEC SHAOXING TECHNOLOGY Co., Ltd. a consolidated subsidiary, in Zhejiang Shaoxing, China.

We develop, manufacture, and sell equipment for manufacturing cutting-edge semiconductors and packages, manufacturing equipment for organic EL and liquid crystal displays, and clean transfer robots.

Semiconductor Manufacturing Equipment Business Unit

Using the know-how and technology cultivated over 40 years, we provide equipment for various processes such as coating, developing, laminating, and peeling in semiconductor manufacturing worldwide.



Transfer Business Unit

Providing various transport systems that are accurate, speedy, and space-saving, including transport robots for silicon wafers, etc., which are essential for semiconductor manufacturing.



Cleaner Business Unit

Providing silicon wafer cleaning and slurry supply equipment, which is an important process in semiconductor manufacturing, as well as equipment that regenerates and reuses phosphoric acid from waste liquid.



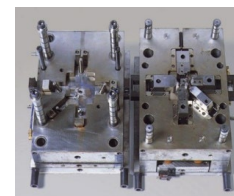
Coater Business Unit

Providing various flat panel manufacturing equipment such as liquid crystal displays. We are currently developing PLP equipment and nanoimprint equipment.



Molding Business

Mold technology, which is essential for parts manufacturing, has been a core technology since our founding, and we provide a variety of products to meet the various needs of user companies.



Surface Treatment Business

Providing plating processing equipment for printed circuit boards incorporated in semiconductor packages and electronic control systems for automobiles, etc.



Attention

Forward-looking statements with respect to TAZMO's business plan, prospects and other such information are based on information available at the time of publication. Actual performance and results may differ significantly from the business plan described here due to changes in various external and internal factors.

This material takes as its objective the provision of information regarding the management policy, plans, and financial situation of TAZMO to shareholders, investors and other visitors. It constitutes neither an offer nor a solicitation to purchase or sell TAZMO stock.

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